

RTG4 Next-Generation Radiation-Tolerant FPGAs

Microsemi Space Forum 2015

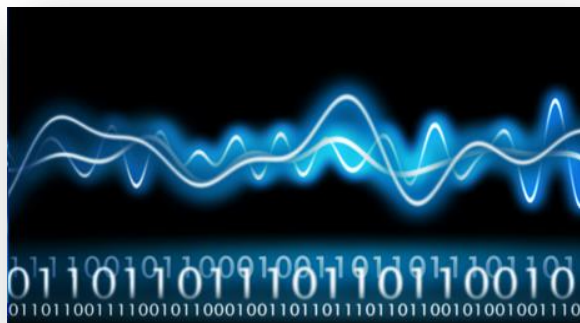
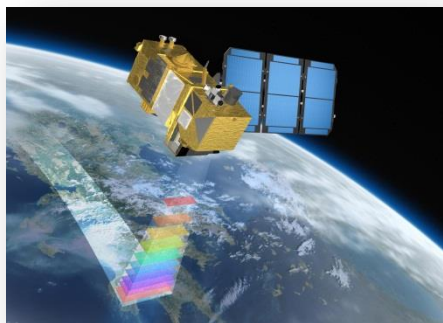
Ken O'Neill
Director of Marketing, Space and Aviation



Microsemi
SPACE FORUM

Satellite Signal Processing Congestion

- Sensor resolution increasing faster than downlink bandwidth
- Satellites required to perform more on-board processing
- Requires high-density, high-performance payload processing electronics



1. Radiation-Hardened ASICs

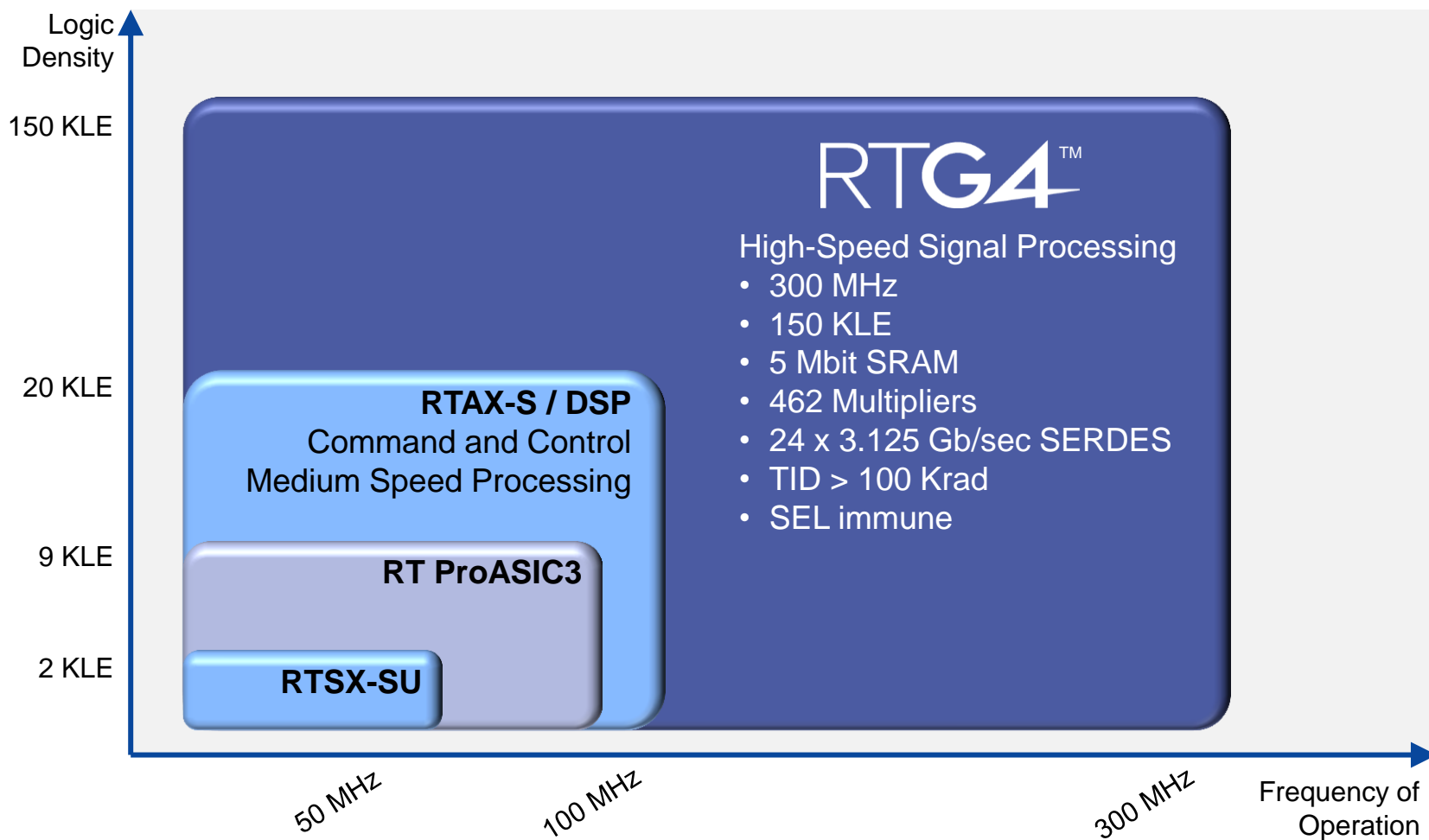
- ✓ High speed, high density, low power
- ✗ Large NRE, relatively low volumes
- ✗ Long development time, long fabrication cycle time
- ✗ High risk of schedule and cost over-runs

2. SRAM FPGAs

- ✓ Easy prototyping, reprogrammable
- ✗ Configuration SEU effects require cumbersome mitigation
- ✗ Increases Size, Weight and Power

Existing solutions for satellite on-board processing have high risks

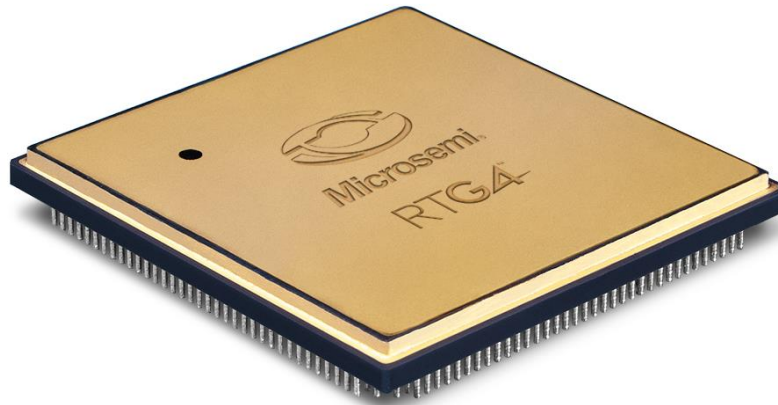
Introducing RTG4 High-Speed RT FPGAs



RTG4 mitigates risks of ASICs and SRAM FPGAs, and has 20X improvement in signal processing throughput

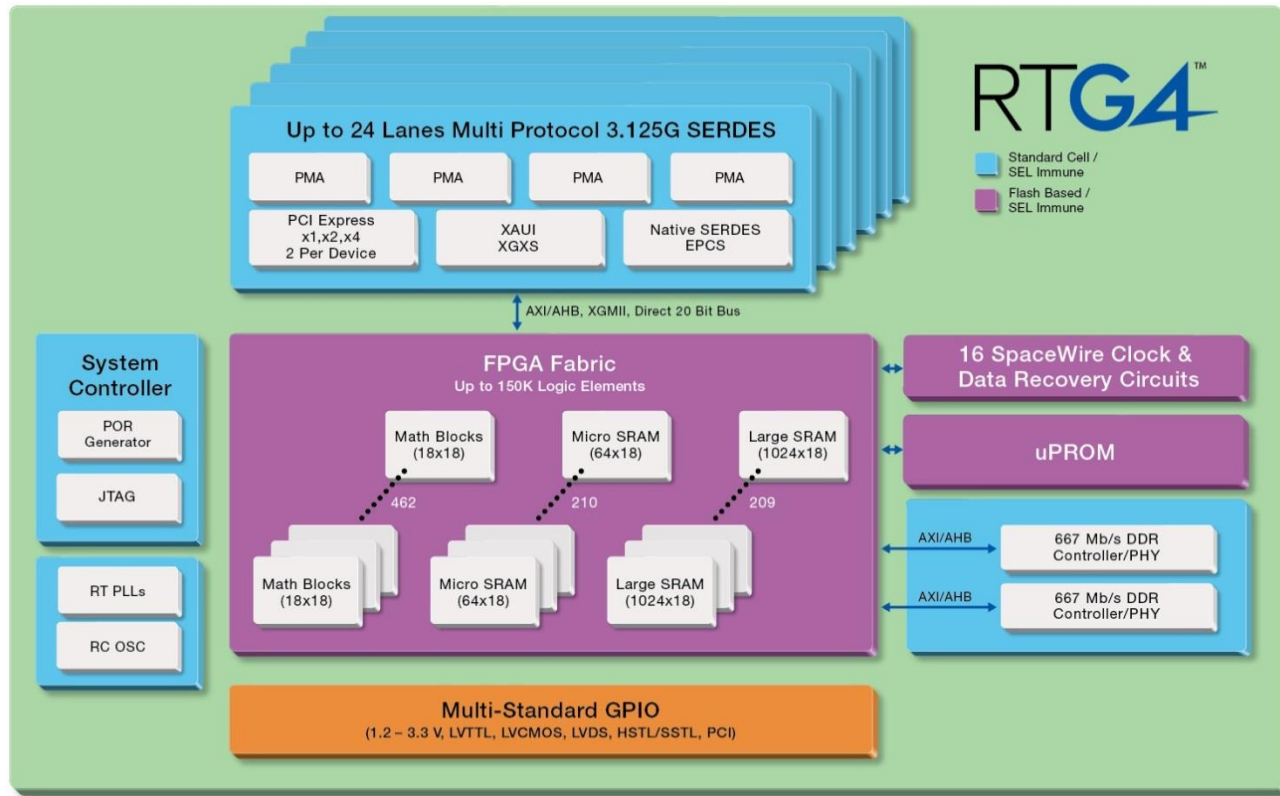
Why RTG4 is Compelling

- More flexible than an RH ASIC
 - Reprogrammable, no NRE, no cost and schedule risk
- More signal-processing features than any other RT FPGA
 - More registers, combinatorial logic, multiply blocks, and transceivers
 - Lower power, live at power-up, no external boot memory needed
- Radiation enhanced for Geosynchronous Earth Orbit and deep space
 - RTG4 65nm Flash has complete immunity to configuration upsets (SEU)
 - Total ionizing dose (TID) and single event effects (SEE) hardened by design



RTG4 offers groundbreaking features for satellite applications

RTG4 Radiation-Mitigated Architecture



- Total-dose hardening of Flash cells
- Single-event hardening of registers, SRAM, multipliers, PLLs

***Comprehensive radiation-mitigated architecture
for signal processing applications***

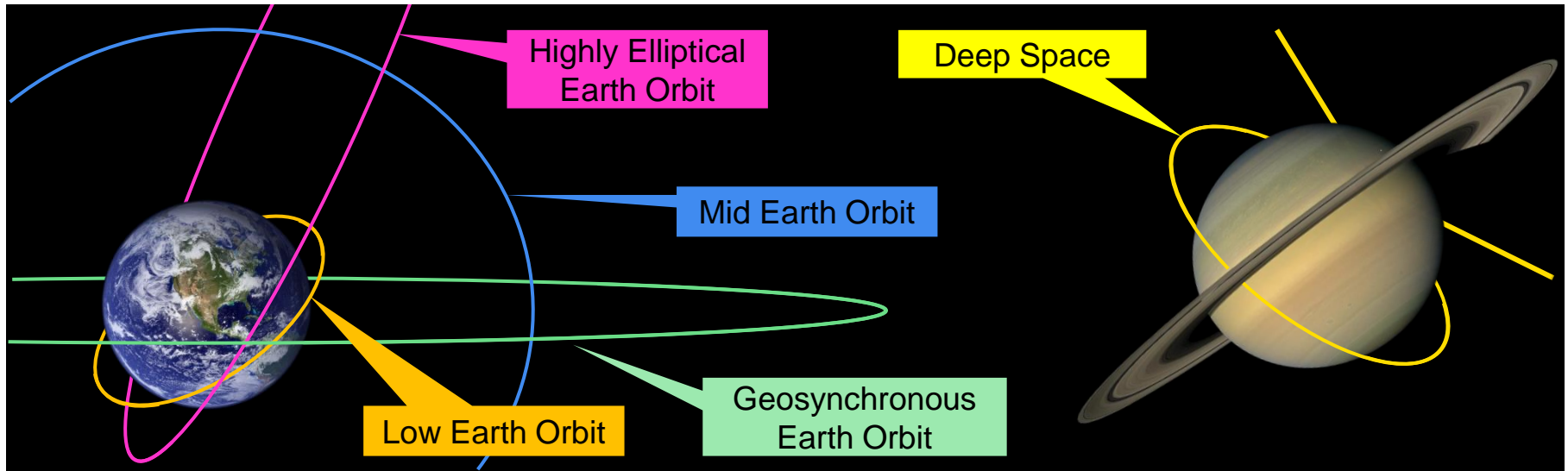
RTG4 Resources

Resources	RT4G150
Logic Elements (TMR Register + 4-Input C Logic)	151,824
18x18 Multiply-Accumulate Blocks	462
RAM Mbits (1.5 Kbit and 24 Kbit Blocks, with ECC)	5.2
UPROM Kbits	381
DDR2/3 SDRAM Controller (with ECC)	2x32
PCI Express Endpoints	2
Globals	24
PLLs (Rad Tolerant)	8
SpaceWire Clock & Data Recovery Circuits	16
User IO (excluding SERDES)	720
SERDES lanes (3.125 Gbit/sec)	24
Hermetic, Ceramic Column-Grid Packages	
CG1657 (Six Sigma Columns)	✓

- RT4G150 is available now in Engineering Samples
- Possible CQFP package – engineering investigation in progress now

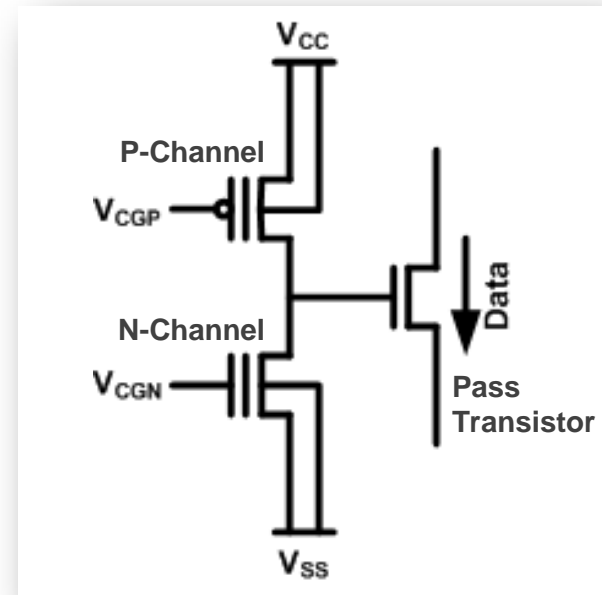
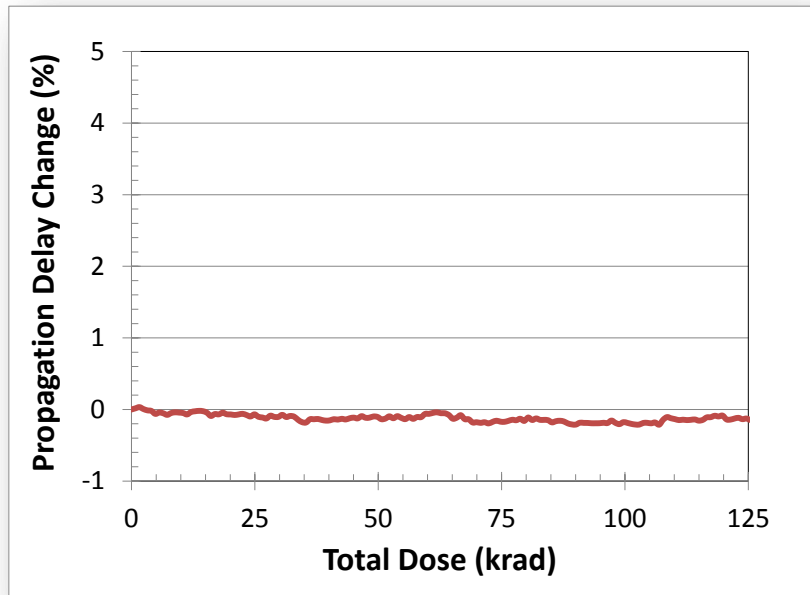
RTG4 Radiation Mitigation

- Radiation hardening by design
 - Total ionizing dose (TID) immune to > 125 kRAD
 - Single event latch-up and configuration upset immune
 - Tested to $103 \text{ MeV-cm}^2/\text{mg}$ (facility limit) at 100°C
 - Single event upsets in fabric $< 1 \times 10^{-11}$ errors/bit/day
 - Single event transient mitigation in logic can be enabled/disabled globally or individually for higher performance

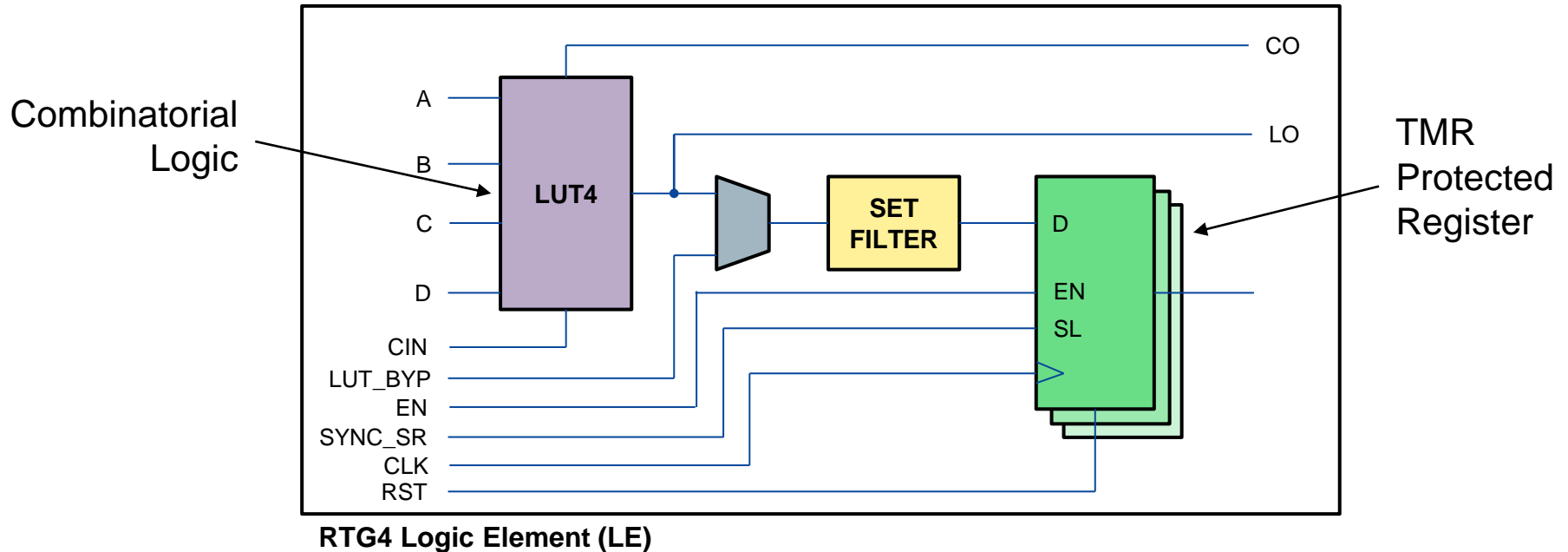


TID Mitigation in RTG4 Flash FPGAs

- RTG4 TID-tolerant interconnect
 - RTG4 FPGAs functional after TID > 125 Krad
 - Change in propagation delay ~ 0% after TID > 125 Krad
 - Pass transistor is indirectly coupled to floating gate devices
 - V_T changes in Flash cells don't change pass transistor prop. delay

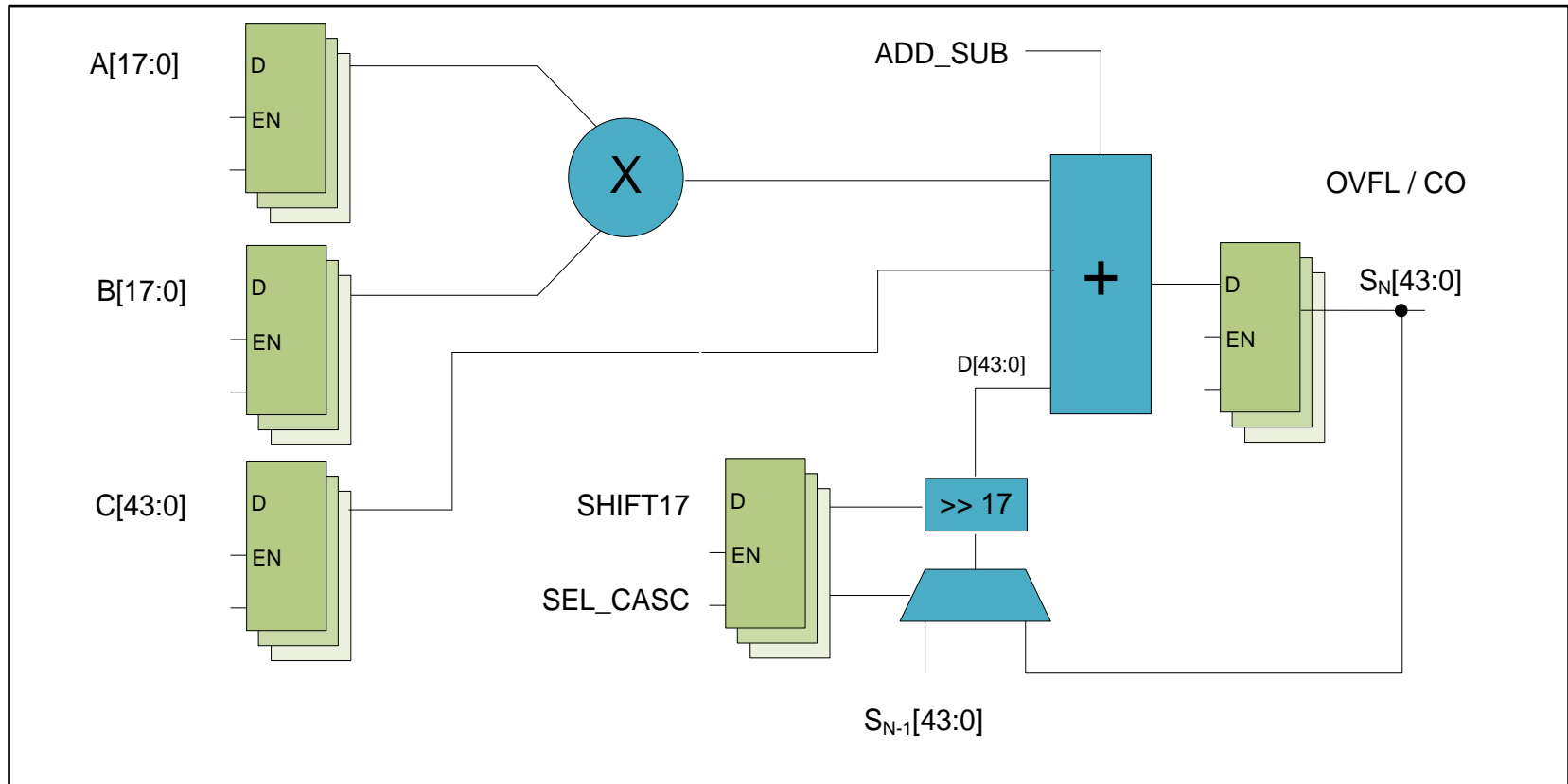


RTG4 Logic Element Radiation Mitigation



- Dedicated register with efficient triple module redundant (TMR) hardening
- Single event transient (SET) filter mitigates radiation glitches from comb. logic
- Hierarchical routing architecture enables >95% module utilization

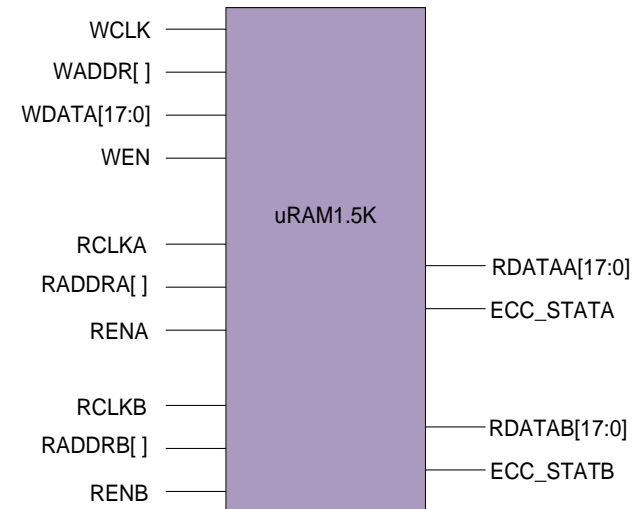
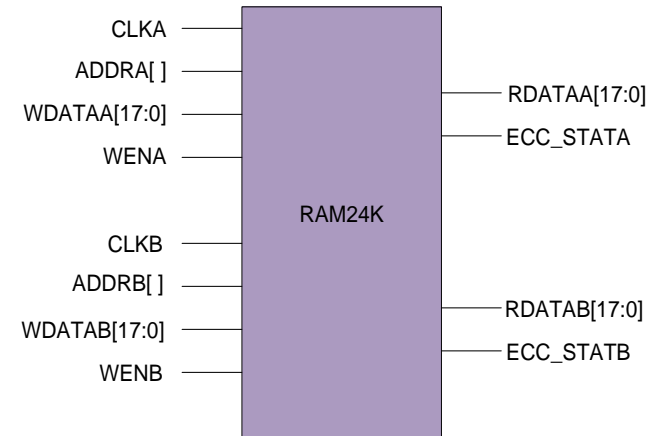
RTG4 Mathblock



- 18 x 18 multiplier with advanced accumulate
- High performance for signal processing throughput
- Optional SEU-protected registers on inputs and outputs (including C input)

RTG4 Memory Blocks

- Radiation Tolerant
 - Resistant to multi-bit upset
 - Built-in optional EDAC (SECDED)
- LSRAM – up to 24 KBit
 - Dual-port and two-port options
 - High performance synchronous operation
 - Example usage
 - Large FFT memory
- uRAM – up to 1.5 KBit
 - Three Port Memory
 - Synchronous Write Port
 - Two Asynchronous or Synchronous Read Ports
 - Example usage
 - Folded FIR filters and FFT twiddle factors

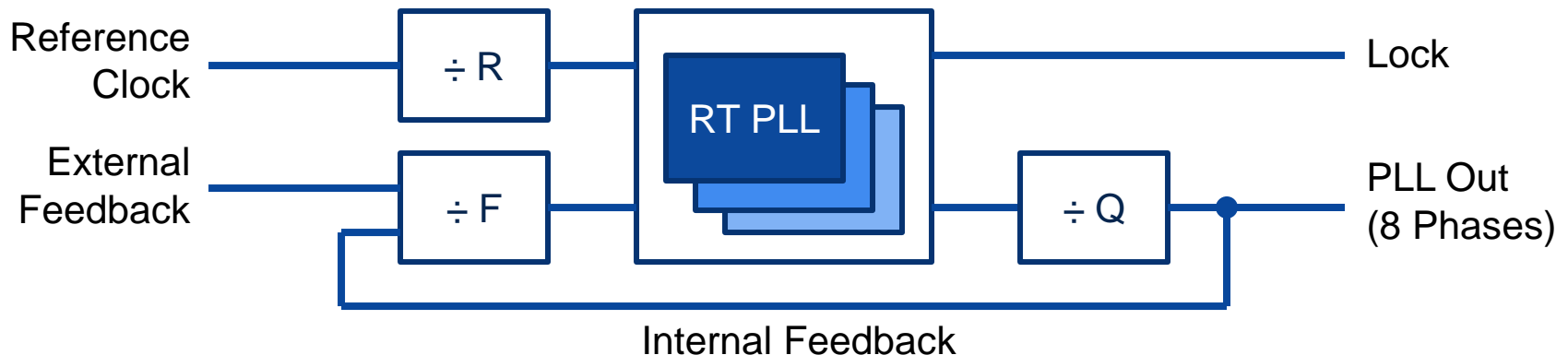


RTG4 General Purpose IO

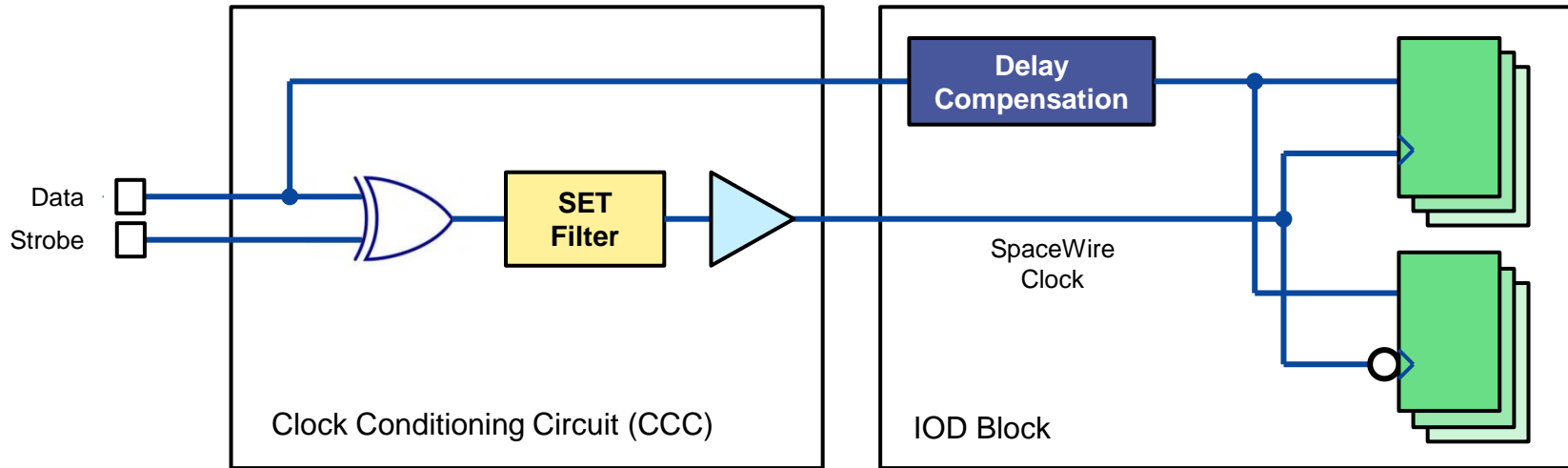
- Single ended standards
 - LVCMOS from 1.2V to 3.3V
 - LVTTTL
 - PCI
- Voltage reference standards (600+ Mbps)
 - Includes on-chip termination
 - SSTL2, SSTL18 and SSTL15
 - For DDR2/DDR3 SDRAM memories
 - HSTL18 and HSTL15
 - For SRAM memories
- Differential I/O standards
 - Includes on-chip termination
 - Mini-LVDS, M-LVDS, RSDS, LVPECL

RTG4 Radiation-Tolerant PLL

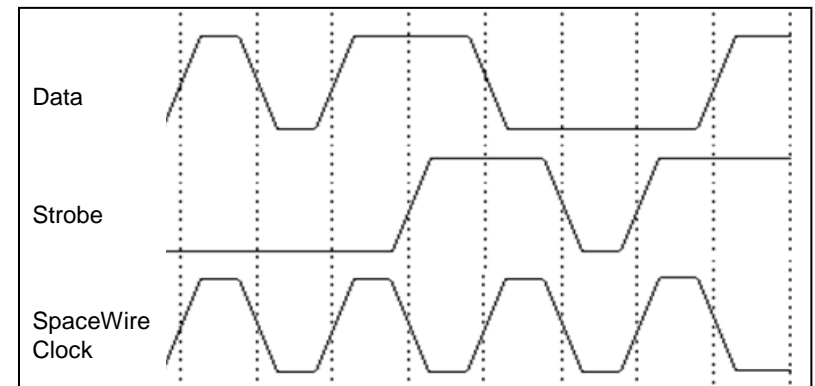
- Radiation-Tolerant PLLs are used in CCC, SERDES and DDR blocks
- Triple module redundant (TMR) PLL in internal feedback mode
 - Reference clock is fed back to all 3 sub-PLLs independently
 - Sub-PLL is SEL immune
- Single PLL in external feedback mode
 - PLL output travels through clock network and is fed back to PLL
 - Common mode used for clock network delay compensation
 - Only 1 sub-PLL is enabled in this mode
 - Sub-PLL is SEL immune



Hardened SpaceWire Clock Recovery



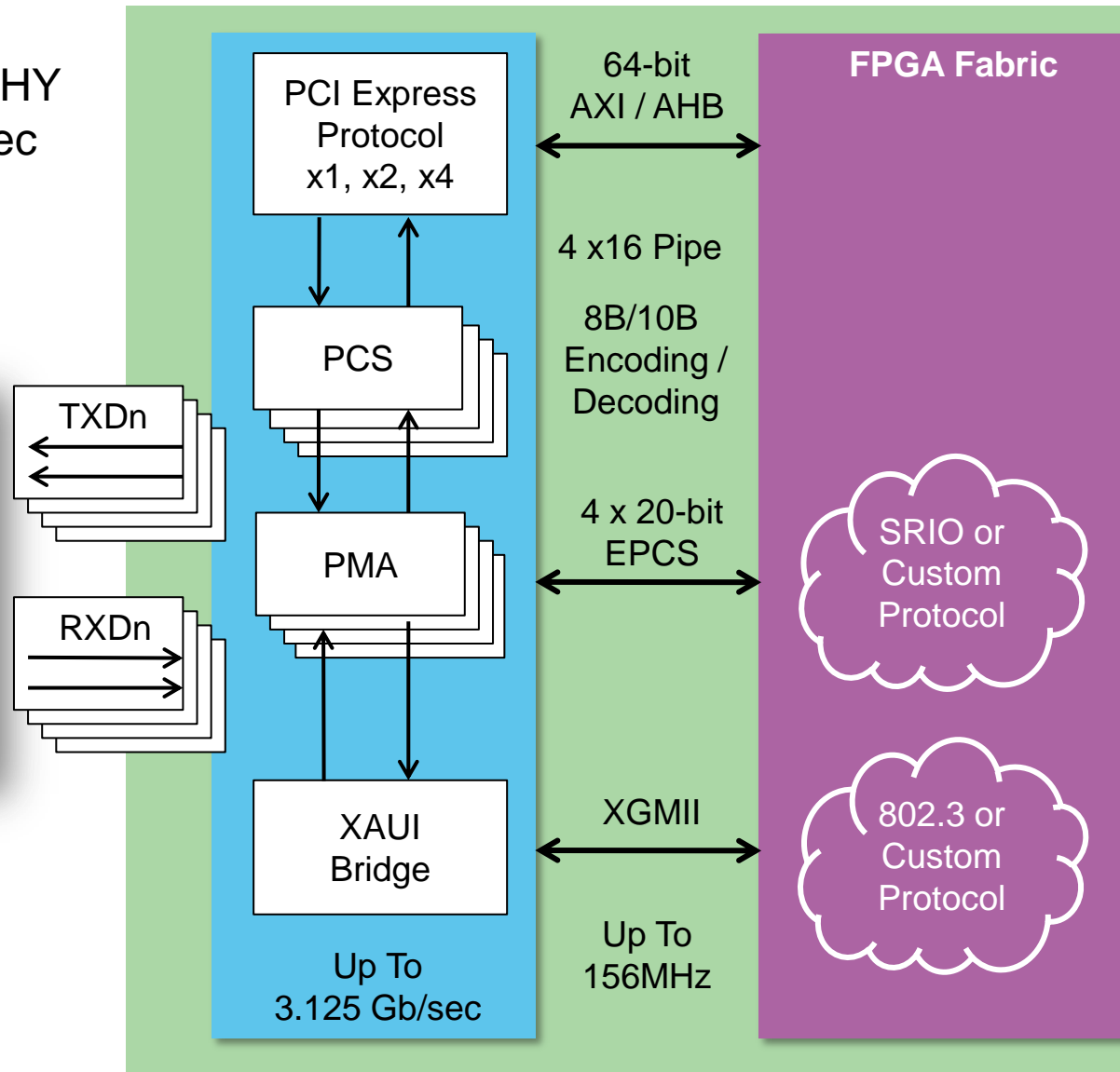
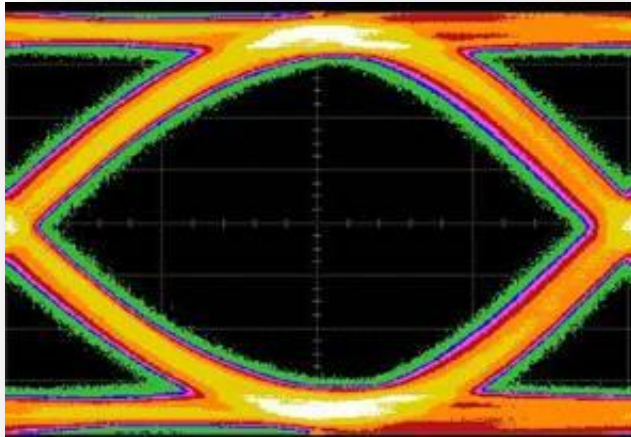
- SpaceWire interface used for command-and-control and data
 - Data and Strobe are XORed to recover SpaceWire clock
 - Hardwired and SET protected
 - Delay compensation available to align data and SpaceWire clock
 - 16 SpaceWire Clock Recovery circuits on each RTG4



Unique Microsemi RTG4 Feature

3.125 Gb/sec SERDES

PMA Based on PCIe Gen 1 PHY
Performance 1 to 3.125 Gb/sec
Up to 6 blocks with 4 lanes



RTG4 Performance

- FPGA logic
 - 250 MHz system performance with SET mitigation
 - 300 MHz system performance without SET mitigation

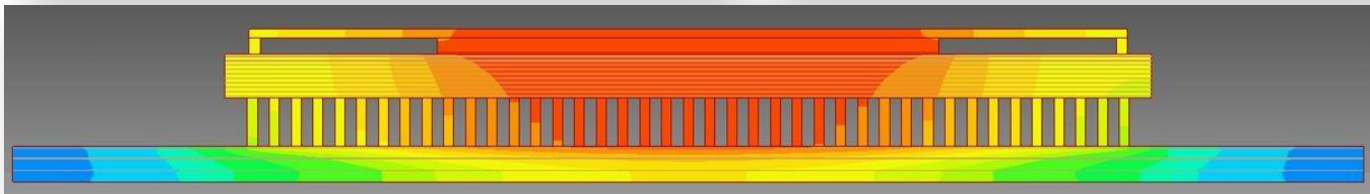
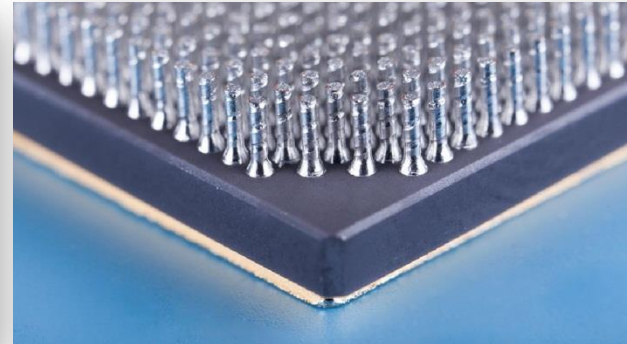
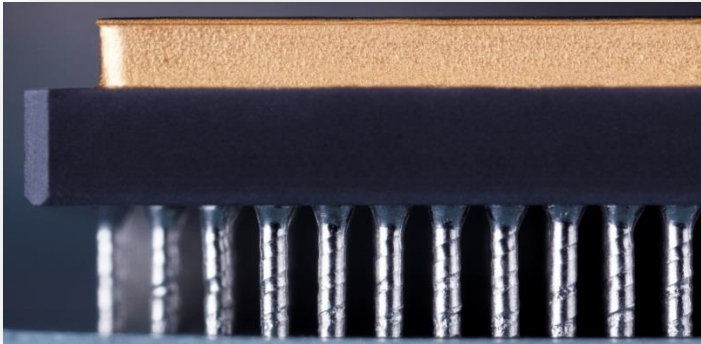
- DSP mathblock
 - 250 MHz pipelined performance with SET mitigation
 - 300 MHz pipelined performance without SET mitigation

- LSRAM24K and uRAM1.5K
 - > 300 MHz

- IO
 - > 600 Mb/sec LVDS and 667 Mb/sec DDR2/3 SDRAM data
 - SERDES > 3.125 Gb/sec

RTG4 Packaging

- Hermetically sealed, ceramic packages
 - Embedded decoupling capacitors
 - Flight models will have Precious Metal Electrode (PME) capacitors
 - Column Grid Array, Ball Grid Array, Land Grid Array



RTG4 Design Ecosystem



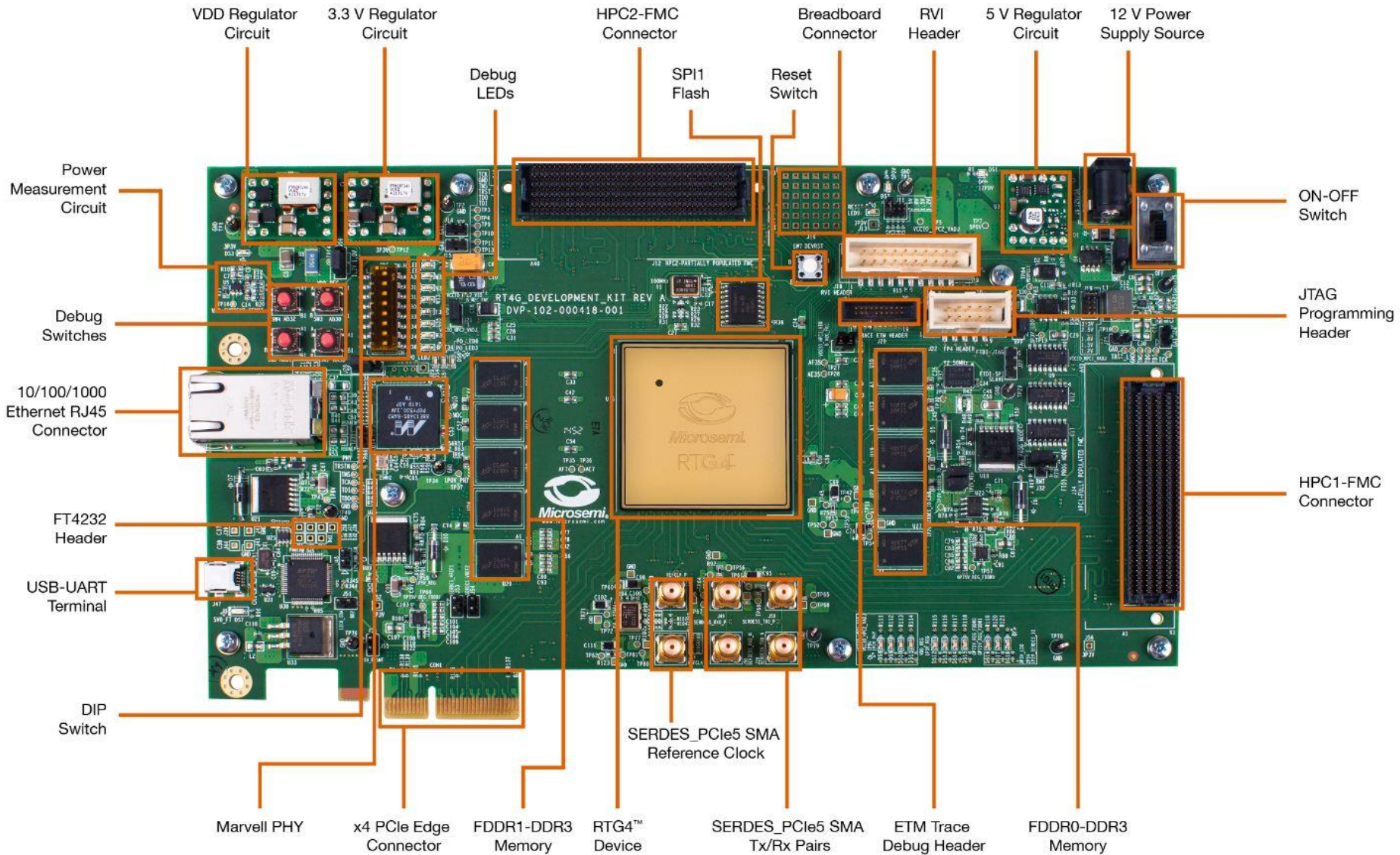
SYNOPSYS
Synplify Pro®
Synphony Model Compiler



- **Libero SoC Design Suite**
 - Synplify Pro® synthesis
 - ModelSim® simulation
 - Power-driven place-and-route
 - SmartPower power analysis
 - SmartTime timing analysis
 - SmartDebug in-circuit FPGA debug

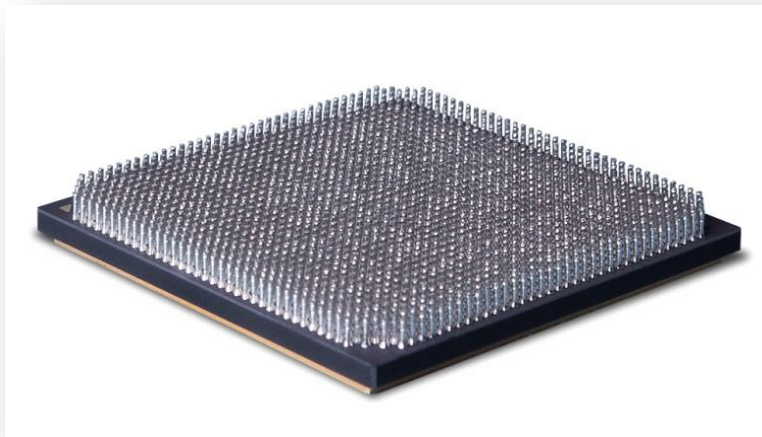
- **Ease of Design Focus**
 - Push button flow - Proceed from synthesis to programming in one click
 - Reduced learning curve
 - Rich IP library & user block support facilitates design reuse
 - Working with IP partners to expand the RTG4 Ecosystem

RTG4 Development Kit

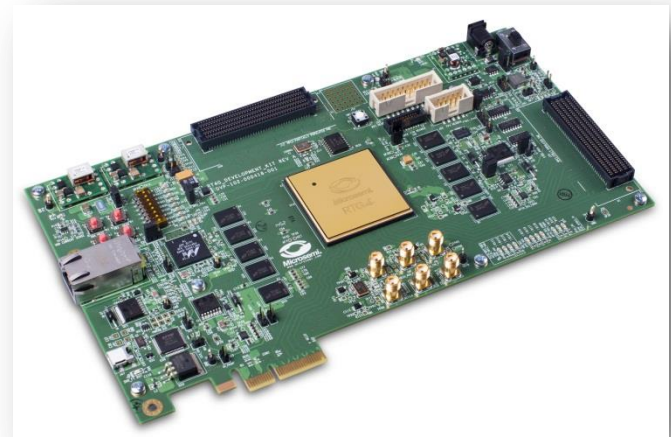


RTG4 Product Availability

- RTG4 devices for space flight applications
 - Engineering Silicon RT4G150 FPGAs: **NOW**
 - Libero SoC Design Software: **NOW**
 - RT4G150 development kit: **NOW**
 - Daisy chain packages: **NOW**
 - MIL-STD-883 class B flight units: First Half 2016
 - QML class Q qualification: End 2016 or Early 2017
 - QML class V qualification: Targeting Late 2017



Ceramic Column Grid Array Package

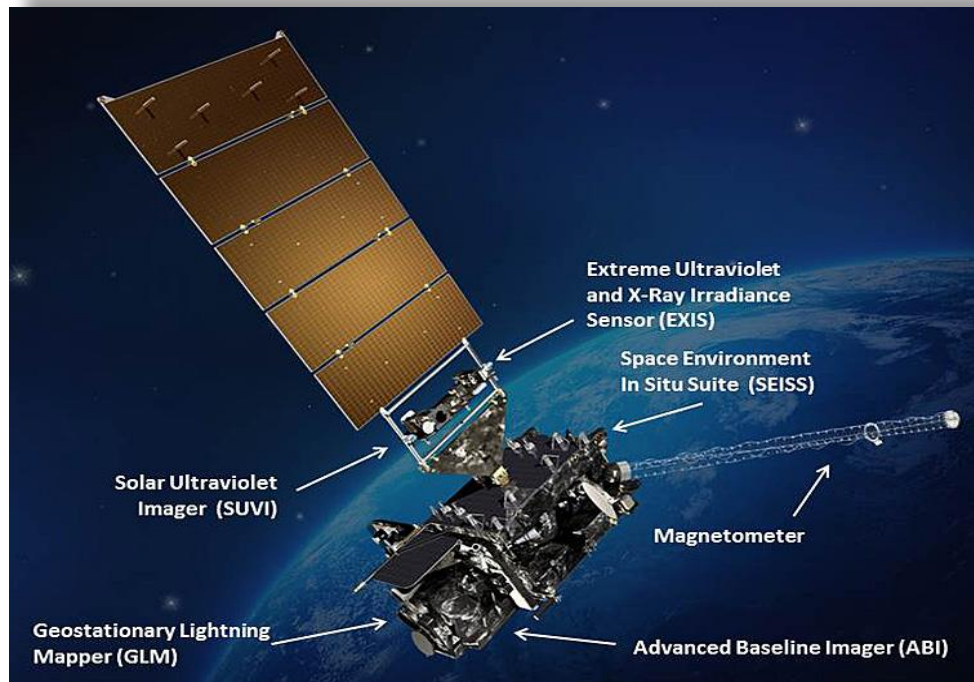


RT4G150 Development Kit

RTG4 in Satellite Applications

Where RTG4 Adds Value

- Roughly 100 remote sensing satellites > 50Kg each year
 - Each may have up to 8 payload instruments
 - Each instrument may require 1 to 12 RTG4 FPGAs

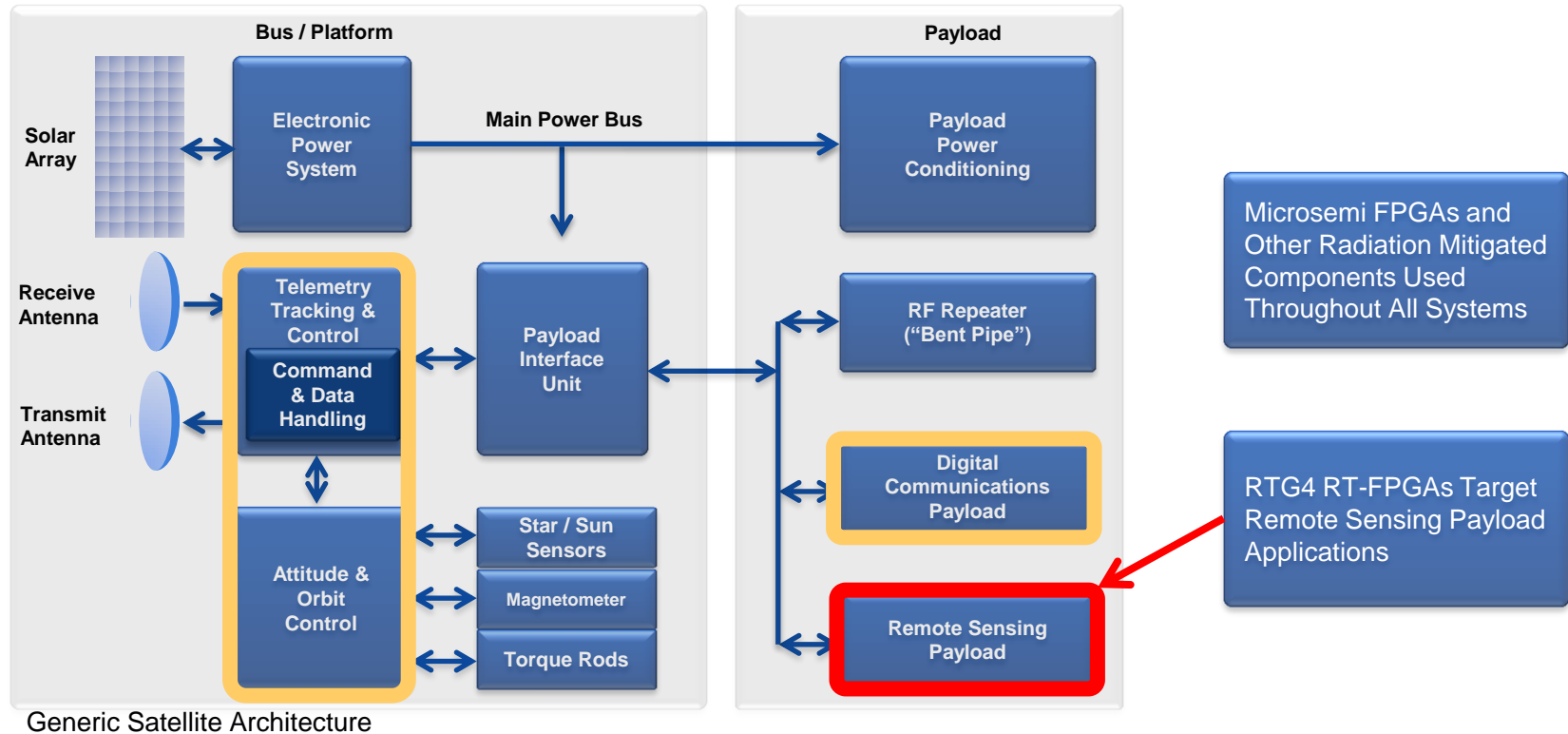


GOES-R Program: 4 satellites, each with 6 instruments

The number of payload instruments which need the flexibility and performance of RTG4 is growing

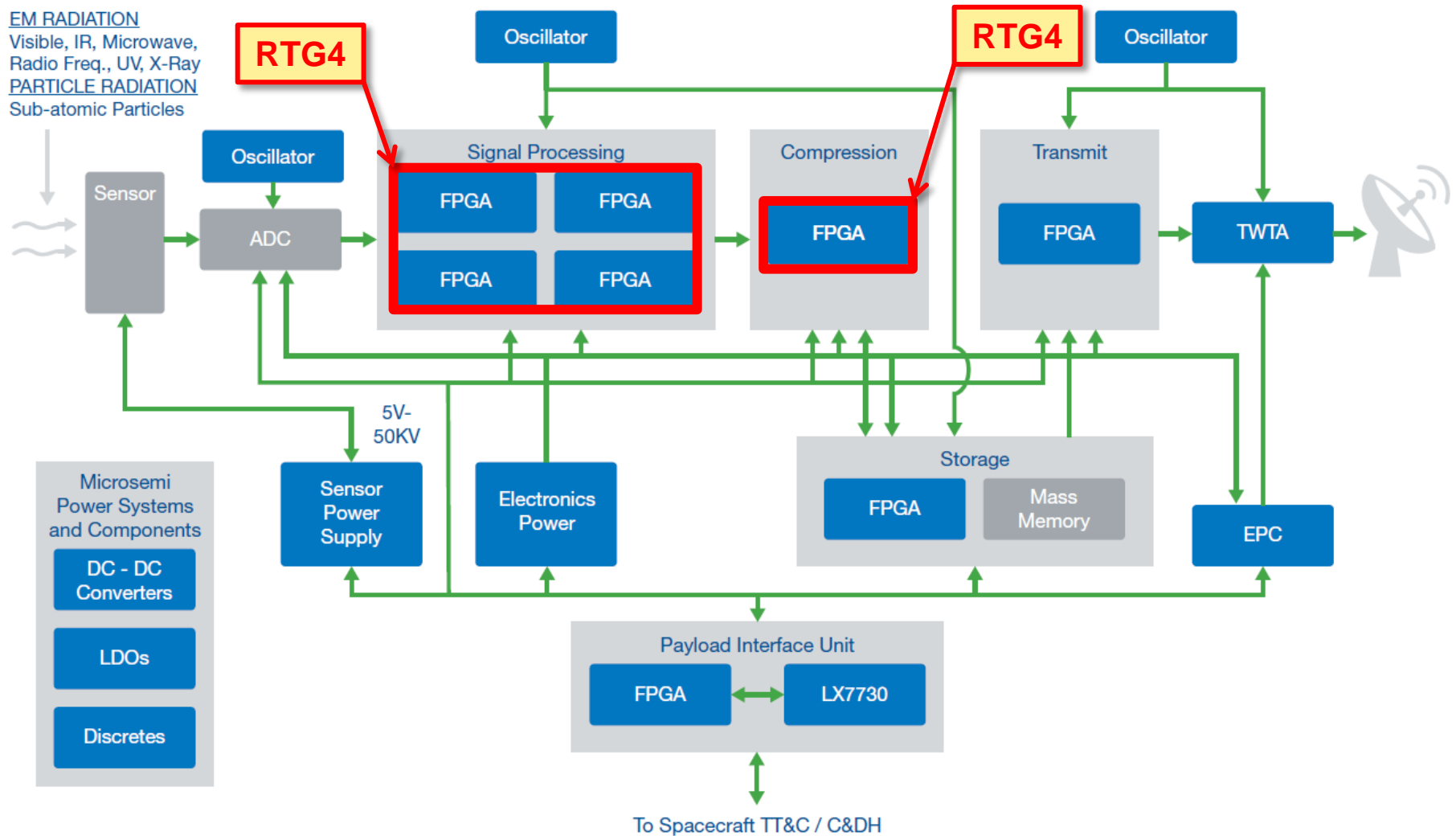
RTG4 Delivers High-Speed Signal Processing

- RTG4 satisfies needs primarily in remote sensing payloads
 - Also adds value in digital communication payloads, and in combined telemetry tracking & control (TT&C) and attitude & orbit control (A&OC) systems
- Microsemi products are found in every system on modern satellites



FPGAs in Remote Sensing Payload

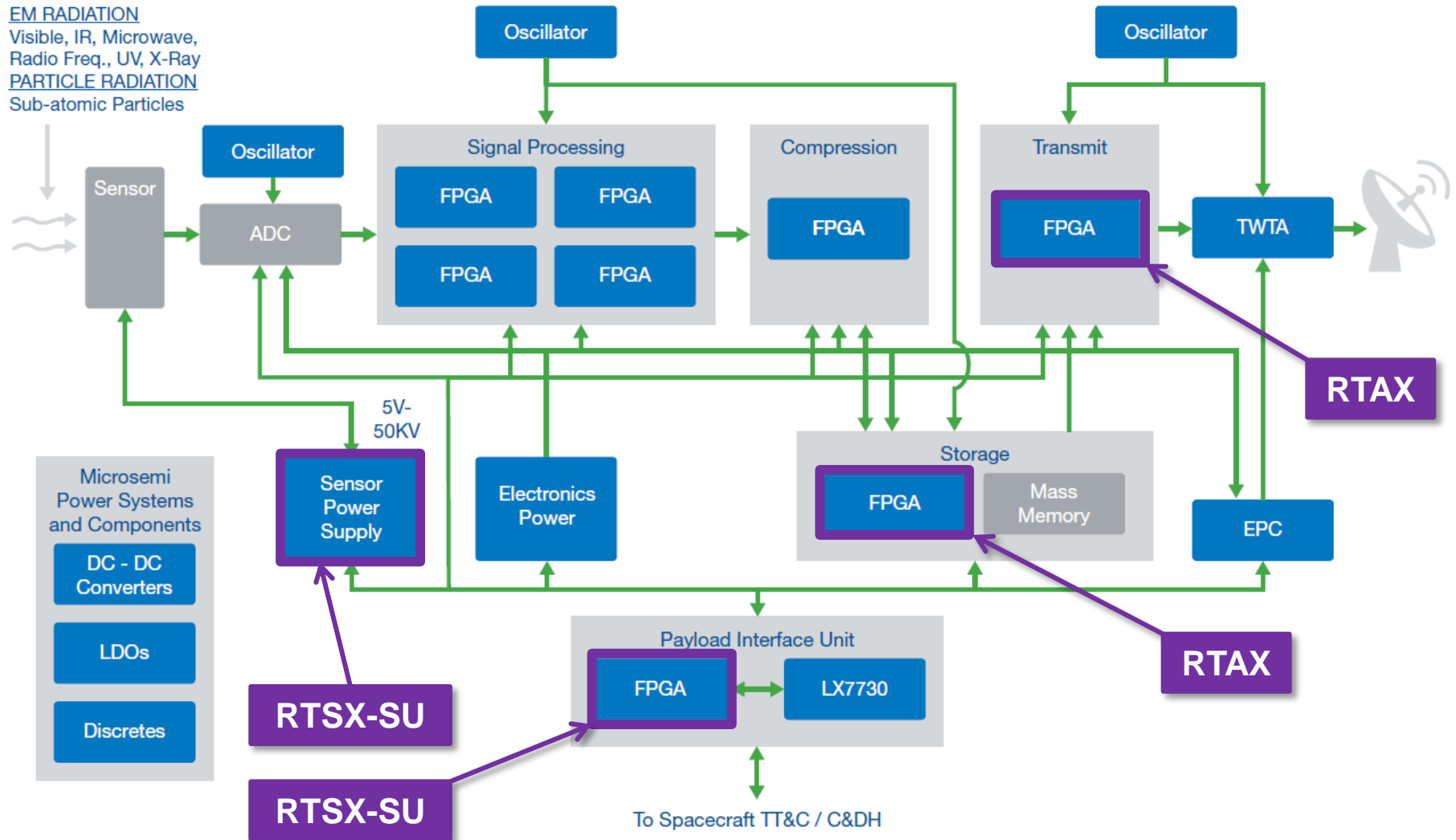
EM RADIATION
Visible, IR, Microwave,
Radio Freq., UV, X-Ray
PARTICLE RADIATION
Sub-atomic Particles



RTG4 complements existing Microsemi Radiation Tolerant FPGAs

FPGAs in Remote Sensing Payload

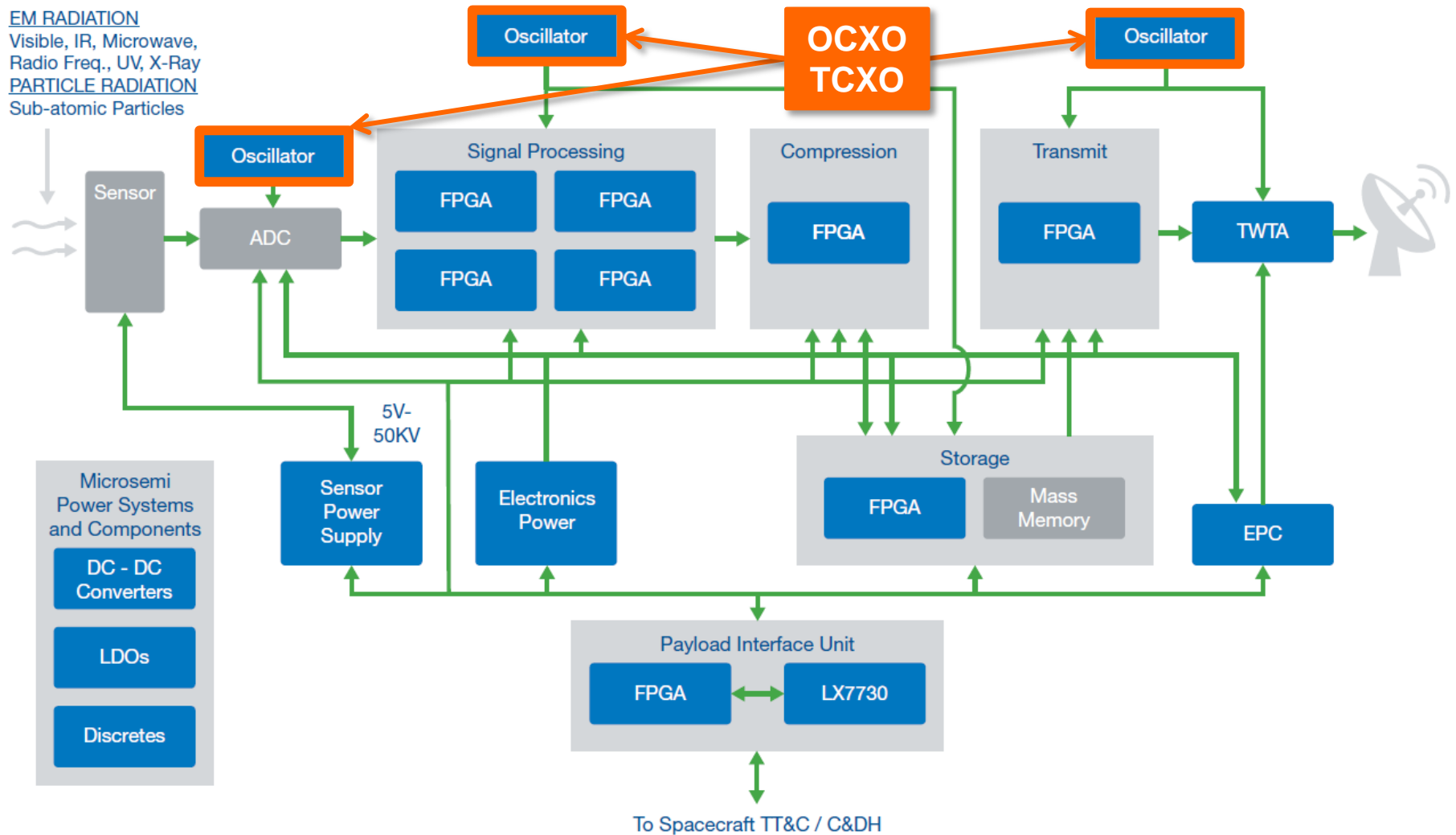
EM RADIATION
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Radio Freq., UV, X-Ray
PARTICLE RADIATION
Sub-atomic Particles



RTG4 complements existing Microsemi Radiation Tolerant FPGAs

Timing Products in Remote Sensing Payload

EM RADIATION
Visible, IR, Microwave,
Radio Freq., UV, X-Ray
PARTICLE RADIATION
Sub-atomic Particles



RTG4 complements other Microsemi space products

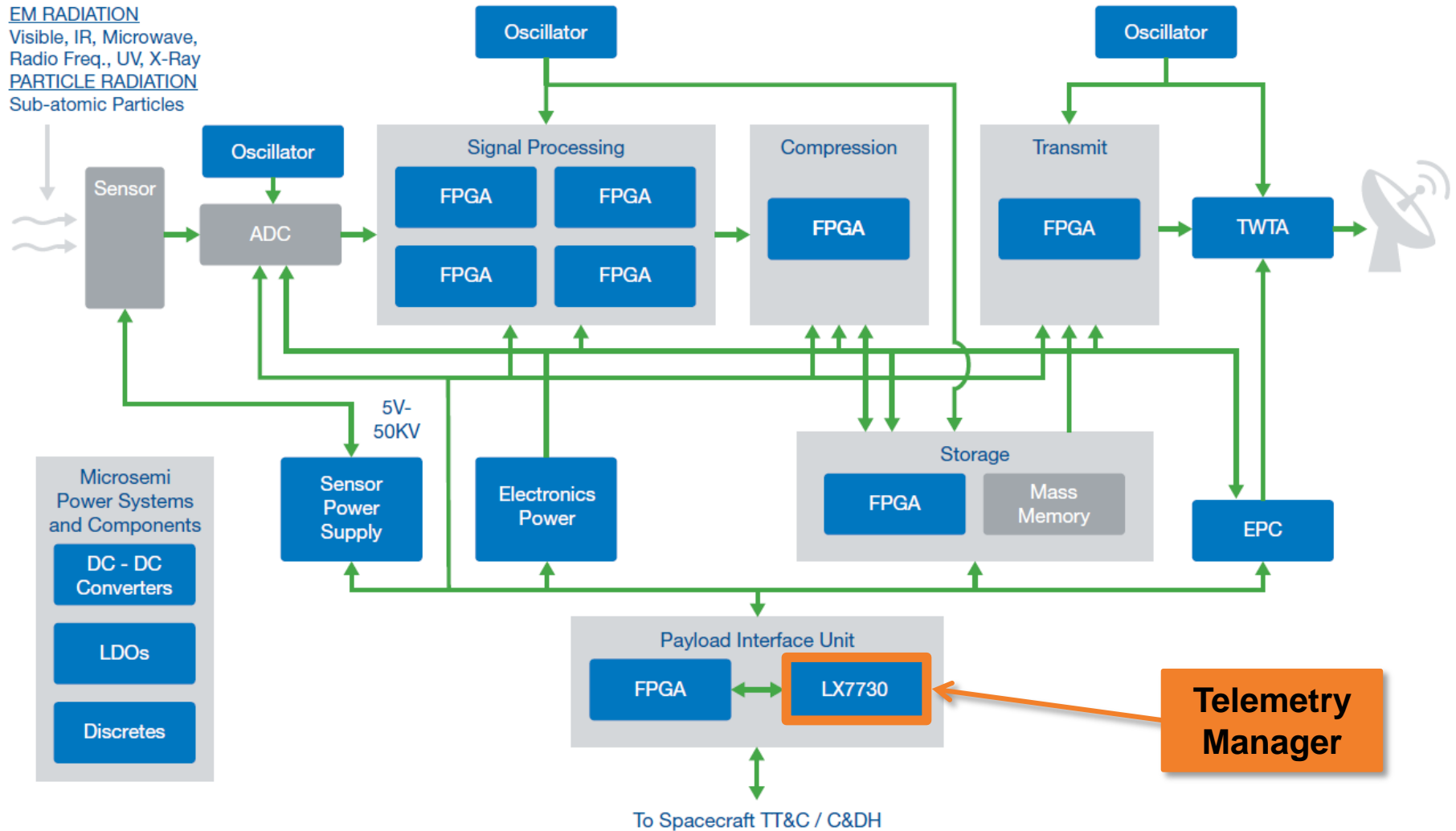
Space System Managers in Remote Sensing Payload

EM RADIATION

Visible, IR, Microwave,
Radio Freq., UV, X-Ray

PARTICLE RADIATION

Sub-atomic Particles



RTG4 complements other Microsemi space products

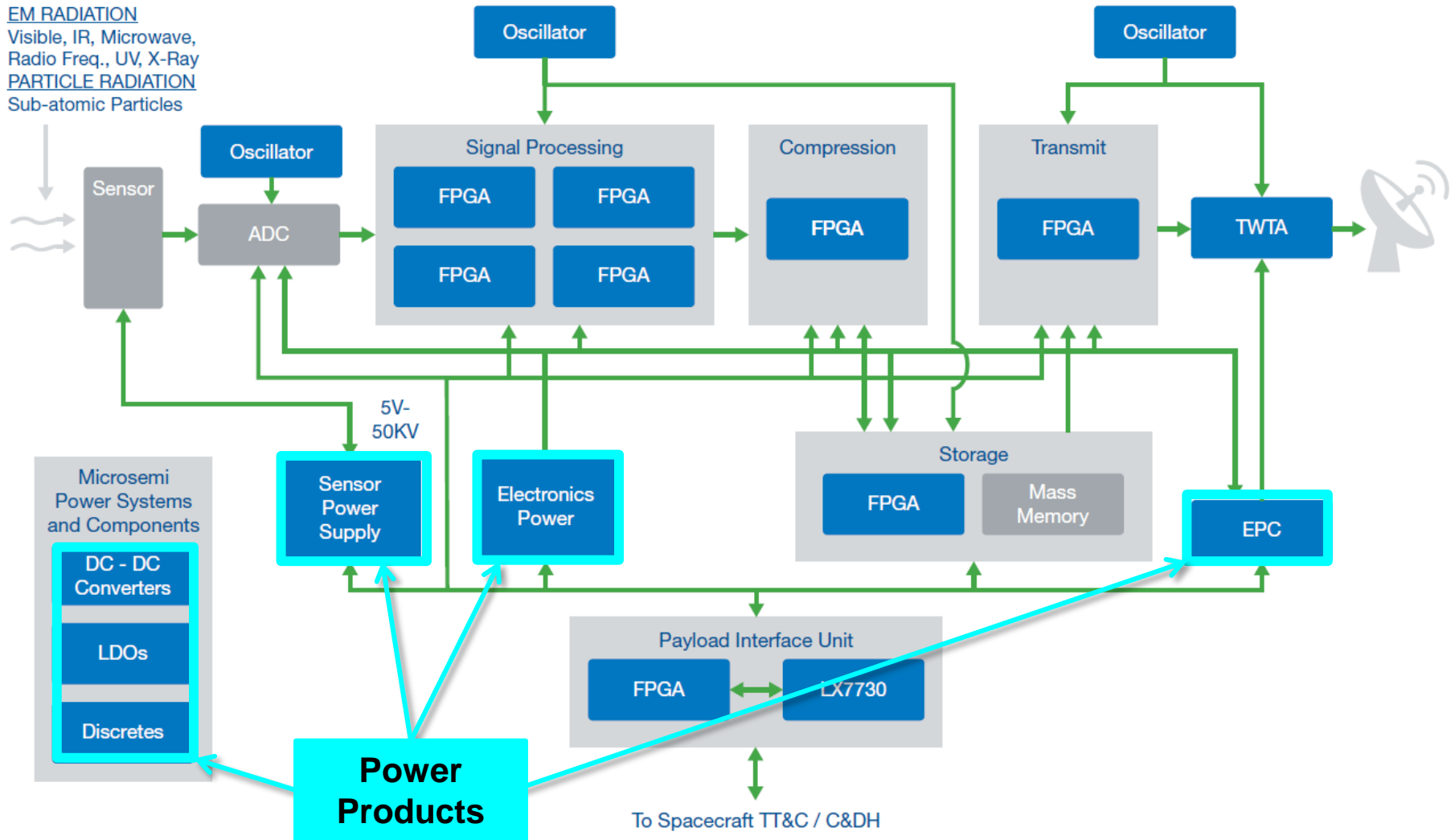
Power Products in Remote Sensing Payload

EM RADIATION

Visible, IR, Microwave,
Radio Freq., UV, X-Ray

PARTICLE RADIATION

Sub-atomic Particles



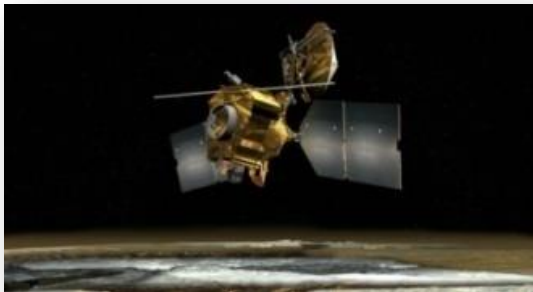
RTG4 complements other Microsemi space products

Microsemi FPGA Space Heritage

■ Microsemi Space

- Broad space portfolio since 1957
- First FPGAs screened for space in 1992
- First FPGAs with radiation hardening by process in 1996
- First FPGAs with radiation hardening by design in 2001

RTSX-SU
(Introduced 2004)



Mars Reconnaissance Orbiter
RTSX-SU on board (2005)

RTAX-S/SL/DSP
(Introduced 2005)



Curiosity (Mars Science Lab)
RTAX on board (2011)

RT ProASIC3
(Introduced 2008)



NASA IRIS
RT ProASIC3 on board (2013)

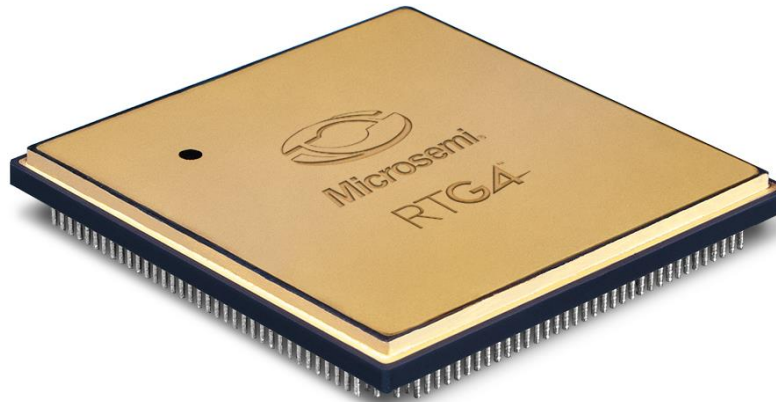
Product Lifetime and Export Control

- Current RT FPGA products – RTAX, RTSX, RT ProASIC3
 - Recent investments in QML qualification of class V and EV-flow
 - Plan to maintain supply (No End Of Life) for at least 10 years

- Update on export control
 - RT FPGAs are no longer controlled under ITAR
 - Export Administration Regulations now apply
 - Managed by U.S. Dept of Commerce
 - All exports require End Use Statement (EUS)
 - An export license may or may not be required
 - Depends on end use and destination country,
 - New Export Control Classification Numbers (ECCNs)
 - RTSX-SU 3A001.a.2.c.
 - RTAX-S/SL/DSP 9A515.e
 - RT ProASIC3 3A001.a.2.c.
 - RTG4 9A515.e

Conclusion

- High-bandwidth signal and data processing in radiation applications
- Flexible and reliable alternative to ASICs
- Immune to radiation-induced configuration upsets
- Radiation enhancements suitable for earth orbits and deep space



Solving Signal Processing Congestion in Space Systems

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Thank You



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Power Matters.™

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